

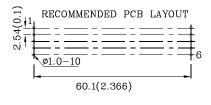
Part Number: XDVG57C

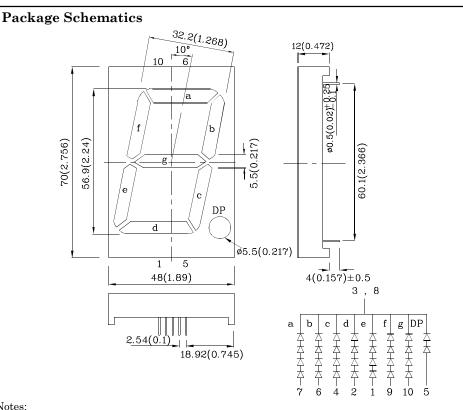
57mm (2.3") SINGLE DIGIT NUMERIC DISPLAY

Features

- \bullet Low power consumption
- \bullet Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white segments
- Optional black face provides superior color contrast
- RoHS Compliant







Notes: 1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted. 2. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)	VG (AlGaInP)	Unit		
Reverse Voltage (Per Chip)		5	V	
Forward Current (Dp)	$I_{\rm F}$	30 (30)	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width (Dp)	ifs	150 (150)	mA	
Power Dissipation (Per Chip)	P_{D}	150	mW	
Operating Temperature	TA	$-40 \sim +85$	°C	
Storage Temperature	Tstg	$-40 \sim +85$		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds			

Operating Characteristics (T _A =25°C)	VG (AlGaInP)	Unit	
Forward Voltage (Typ.) (Dp) (I _F =10mA)	V_{F}	8.0 (4.0)	V
Forward Voltage (Max.) (Dp) (I _F =10mA)	V_{F}	10 (5.0)	V
Reverse Current (Max.) (Per Chip) ($V_R=5V$)	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λP	574*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA)	λD	570*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	$ riangle \lambda$	20	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	pF

Part Number	Emitting Color	Emitting Material	Luminous CIE127 (I _F =10m	-2007*	Wavelength CIE127-2007* nm λP	Description
			min.	typ.		
XDVG57C	Green	AlGaInP	88000 31000*	199990 61990*	574*	Common Cathode, Rt. Hand Decimal

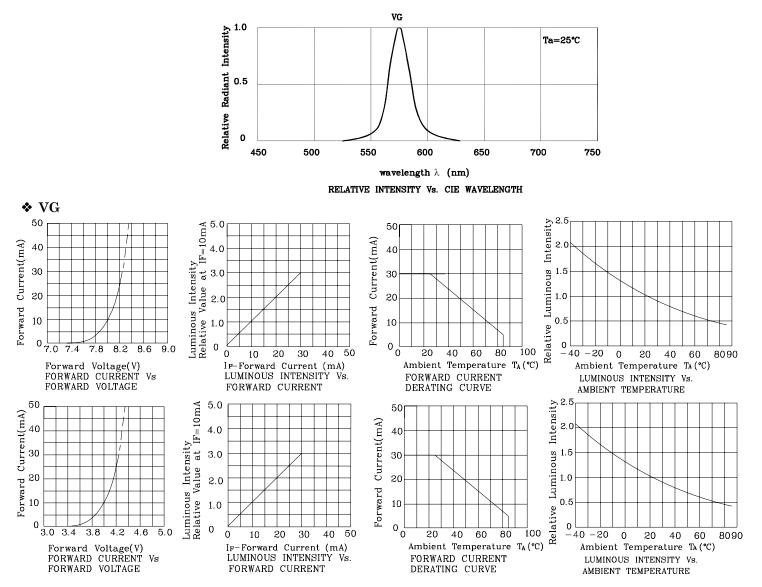
*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards. Mar 11,2014

XDSB7721 V1-X Layout: Maggie L.

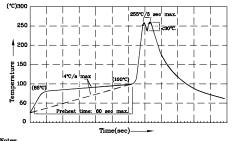


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Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



Nouss: 1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 280°C 2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec

 Peak wave soldering temperature between 245° ~ 255° for 3 max.
Do not apply stress to the epoxy resin while the temperature 4. Fixtures should not incur stress on the component when mou during soldering process.
SAC 305 solder alloy is recommended.
No more than one wave soldering pass. 85°C ountin

During wave soldering, the PCB top-surface temperature should be kept below 105°C.

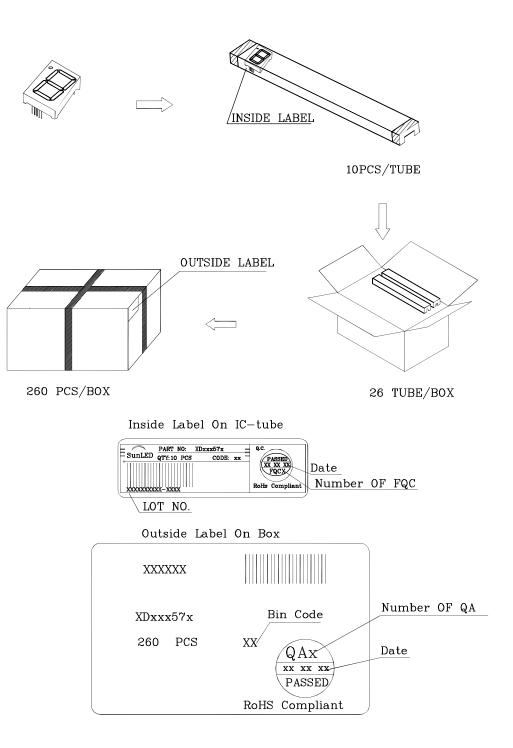
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

- the typical accuracy of the sorting process is as follows:
- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V
- Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS



TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet.
- User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The contents within this document may not be altered without prior consent by SunLED.
- 6. Additional technical notes are available at <u>http://www.SunLEDusa.com/TechnicalNotes.asp</u>